

1234

A

B

C

D

SL

1.061 MM +/- 10%

CL

1

2

3

4

1

2

3

4

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	62	YES
×	2	36	0.91	14	YES
□	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT

STACK-UP FOR REFERENCE

LAYER 1 L1 TOP

CORE

LAYER 4 L16 BOTTOM

18 UM CU + 12.5 UM PLATING (30.5 UM)

1.0 MM CORE FR-4 LG 135 INCLUDING COPPER

18 UM CU + 12.5 UM PLATING (30.5 UM)

NOTES:

1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TG 135 EPOXY LAMINATE WITH 18 UM COPPER PLATING AND 1 MM THICKNESS.

2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE

3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.

4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.

5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.

6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY. EQUIVALENT WET OR DRY FILM MAY BE USED.

7. SILKSCREEN BOARD USING BLACK INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE

8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:

\* 2 COPPER LAYERS

\* 1 MM BOARD THICKNESS

\* REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

Domino Core

Domino Pi

Domino Qi

CC

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Domino JTAG SPI

24/08/14 12:24

Component Assembly SOL (.ASS)

Rev. B

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